



Layer	Stack up	Supplier	Supplier Description	Description	Resin Content	εr	Type	Copper Layer Type	Base Thickness	Processed Thickness	Impedance ID	Notes-1	Stock Number
1		CIREXX	SM/005	LPI		4.200	SOLDER MASK			0.500			500-005
		Isola	half oz	Copper Foil 0.7			Copper	Mixed	0.700	2.100	1	0	
		ISOLA	370 HR*	7628	45.000	4.300	PREPREG		7.300	7.265			
		ISOLA	370 HR*	7628	45.000	4.300	PREPREG		7.300	7.265			
2								Plane	1.400	1.400			
3		ISOLA	4-7628	FR408	40.000	3.940		Plane	28.000	28.000			
									1.400	1.400			
		ISOLA	370 HR*	7628	45.000	4.300	PREPREG		7.300	7.265			
		ISOLA	370 HR*	7628	45.000	4.300	PREPREG		7.300	7.265			
4		Isola	half oz	Copper Foil 0.7			Copper	Mixed	0.700	2.100	0		
		CIREXX	SM/005	LPI		4.200	SOLDER MASK			0.500			500-005

Copper Thickness = 7.000 | Dielectric Thickness = 57.060 | Solder Mask Thickness = 1.000 | Stack Up Thickness = 64.060 | Stack Up Thickness with Soldermask = 65.060

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Upper Trace Width (W2)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)	CI Notes-1
	1	Coated Coplanar Waveguide With Lower Ground 1B	1	2	0	14.000	13.500	0.000	5.400	50.020	50.000	10.000	

Drill Image	1st Layer	2nd Layer	Drill Type	Minimum Size	Fill Type
	1	4	Mechanical PTH	8.000	Non-Conductive

Notes

StackName: Master	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1	
Date: 1/21/2020	Associated Documents:						
Author:							
Department: PLANNING							
Site: SANTA CLARA							